Time	TUTORIAL Topics (General Review)	Lecturers
13:00-13:05	Opening remark from SPST	Prof. Takao Watanabe (University of Hyogo)
13:05-13:10	Opening remark from TAPJ	Prof. Hideo Horibe (Osaka Metropolitan University)
13:10-14:40	Introduction to EUV Lithography	Dr. Harry Levinson (HJL Lithography)
14:40-14:55	Break	
14:55-15:25	The Physics of the Exposure of Photoresists to Extreme Ultraviolet (EUV, 13.5 nm) Light (From the Perspective of a Chemist)	Prof. Robert Brainard (State University of New York)
15:25-15:55	Using Resist Lithographic Responses to Map the Projected Image for Material Evaluation and Process Design	Prof. John Petersen (imec)
15:55-16:25	PFAS Free Sustainability	Mr. Tomohide Katayama (Merck)
16:25-16:40	Break	
16:40-17:20	Why Are Photosensitive/Non-Photosensitive Polymers Important in Advanced Semiconductor Packaging?	Prof. Fukushima Takafumi (Tohoku University)
17:20-17:50	Advanced Packaging Materials and Co-Creative Evaluation Platforms at Resonac	Dr. Sadaaki Katoh (Resonac)
17:50-18:20	Photopolymers Enabling Fine-Pitch Cu RDL Damascene: Materials, Process, and Integration	Dr. Toshiyuki Ogata (Taiyo Holdings)
18:20-18:25	Closing remark	Dr. Seiji Nagahara (ASML Japan)
18:30-20:00	Welcome Reception Free of charge 無料	